



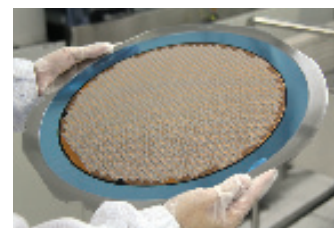
About STATS ChipPAC

STATS ChipPAC (SGX-ST: STATSchP) is a leading service provider of semiconductor packaging design, bump, probe, assembly, test and distribution solutions. We have the scale to provide a comprehensive range of semiconductor packaging and test solutions to a diversified global customer base servicing the computing, communications and consumer markets.

Technology and Services

With a broad technology portfolio ranging from leadframe to laminate, flip chip, wafer level and advanced 3D packaging solutions, STATS ChipPAC provides innovative and cost effective semiconductor solutions. STATS ChipPAC has a leadership position in advanced package technology including fan-in and fan-out wafer-level packaging, flip chip interconnect, 3D integration and Through Silicon Via (TSV) to meet the increasing market demand for next-generation devices with higher levels of integration, increased functionality and compact sizes.

As a full turnkey service provider, STATS ChipPAC provides wafer probe and final testing on a diverse selection of testers covering the major test platforms in the industry and has proven expertise in testing a broad range of semiconductors, especially mixed-signal, radio frequency (RF), analog and high-performance digital devices.



Business Highlights

Operations

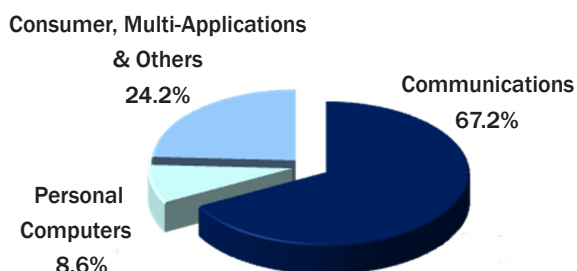
STATS ChipPAC's manufacturing facilities are located in strategic semiconductor markets including South Korea, Singapore, China, Malaysia and Taiwan. Our close proximity to the major hubs of wafer fabrication allows us to provide customers with fully-integrated, multi-site packaging and test services.

We market our services through a direct sales force and customer support teams in the United States, Singapore, South Korea, Japan, China, Taiwan and Switzerland.

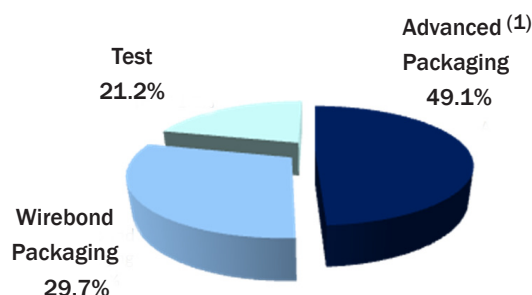


Note: 4,118 wire bonders and 948 testers as of 1Q 2014

1Q 2014 Revenue by End User Market



1Q 2014 Revenue by Product Line



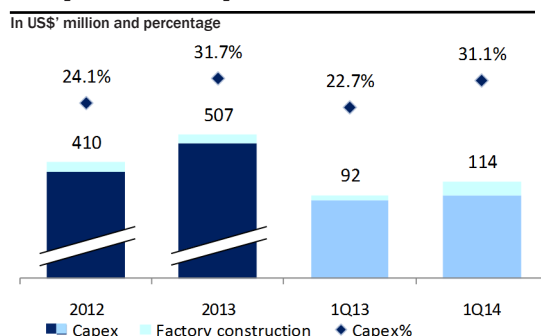
(1) Advanced Packaging includes flip chip and wafer level packaging.

Financial Highlights

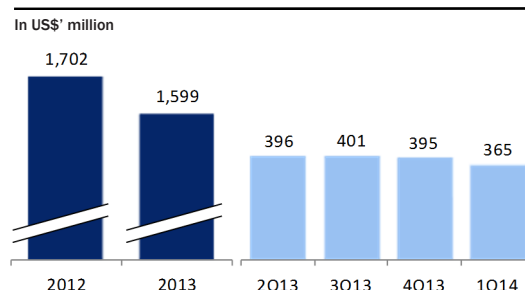
1Q 2014 Financial Results

- Advanced packaging grew to 49% of revenue
- Progress on strategic growth initiatives in advanced wafer level technologies
- eWLB gaining recognition as a technology of choice for high performance, super-thin packages with advanced system level integration for the mobile market

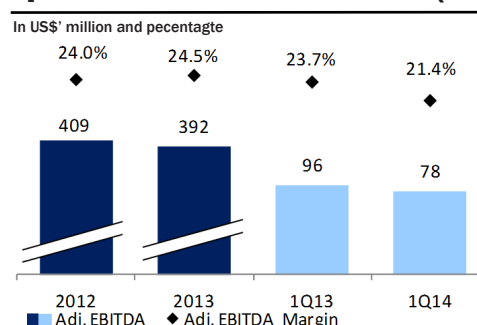
Capex and Capex as % of Revenue



Revenue



Adjusted Earnings Before Interest, Taxes, Depreciation and Amortization (EBITDA)⁽¹⁾



Note: (1) Adjusted EBITDA is defined as net income attributable to STATS ChipPAC Ltd. plus income tax expense, interest expense, net, depreciation and amortisation, restructuring charges, share-based compensation, goodwill and equipment impairment, tender offer, debt exchange or debt redemption expenses and write-off of debt issuance costs. Adjusted EBITDA excludes the plant closure costs related to our Malaysia plant and our restructuring actions.

Recent Headlines

- 28 Apr 14 STATS ChipPAC Conferred Singapore's Prestigious Distinguished Partners in Progress Award
- 14 Apr 14 STATS ChipPAC Appoints New Chief Financial Officer
- 11 Mar 14 STATS ChipPAC Introduces Breakthrough Manufacturing Method for Wafer Level Packaging
- 26 Feb 14 STATS ChipPAC's fcCuBE[®] Technology Achieves Significant Growth in 2013
- 21 Jan 14 STATS ChipPAC Recognised for Patent Innovations for the Third Consecutive Year by IEEE

Corporate Information

Executive Management

Tan Lay Koon, Director, President and Chief Executive Officer
 Wan Choong Hoe, Executive VP and Chief Operating Officer
 Dr. Han Byung Joon, Executive VP and Chief Technology Officer
 Hal Lasky, Executive VP and Chief Sales Officer
 Dennis Chia Choon Hwee, Senior VP and Chief Financial Officer
 Chong Khin Mien, Senior VP, Product and Technology Marketing
 Janet Taylor, Senior VP, General Counsel and Company Secretary

Investor Relations Contact

Tham Kah Locke
 Vice President of Corporate Finance
 email: kahlocke.tham@statschippac.com
 Phone: (65) 6824 7788
 Fax: (65) 6720 7826

Corporate Headquarters

STATS ChipPAC Ltd.
 10 Ang Mo Kio Street 65
 Techpoint #05-17/20
 Singapore, 569059
www.statschippac.com

Stock Information

Singapore Exchange Securities
 Trading Limited (SGX-ST)
 Ticker: STATSchP

